





The OX-172 is a high stability ovenized crystal oscillator characterized for IEEE-1588 PTP applications in a 28 x 38 mm package. Driven by an SC cut crystal, the oscillator provides TDEV and MTIE values that exceed the GR1244 system performance requirements when locked through a 1 mHz bandwidth. The OX-172 is designed for operation during congested network conditions, when the frequency and quality of the packet information is degraded. The OX-172 is a member of the OX-17 oscillator series. Other oscillators in the series include the OX-170 standard oscillator, OX-171 high stability oscillator, and the OX-174 and OX-175 low phase noise oscillators. The Microsemi design team will also help develop custom solutions where performance optimization is required for specific applications. Please contact the factory for customization options.

Features

- Reflow Process Compatible
- SC-Cut resonator
- Temperature stability to 2 ppb peak to peak
- Best in class MTIE and TDEV
- Optimized to support timing over packet applications
- Standard Frequencies: 10, 12.8, 20 MHz

Applications

- SETS clock support
- Edge and Core routers

Performance Specifications

Frequency Stabilities¹ (Stabilities listed for 10 MHz. For stabilities above 10 MHz values may degrade. Please contact factory) **Typical** Units Condition **Parameter** Min Max **Overall Stability** -1.0 +1.0 Free run accuracy (20 years all conditions) ppm over 24 hours and ±3.0°C Drift -0.3 +0.3 ppb 2 -20 to +70°C vs. Operating Temperature ppb pk-pk Range (referenced to +25°C) -40 to +85°C 4 ppb pk-pk Initial Tolerance -500 +500 at time of shipment ppb -0.5 vs. Supply Voltage Change +0.5 $V_s \pm 5\%$ ppb vs. Load Change -0.5 Load ±5% +0.5 ppb +1 vs. Aging / Day -1 after 24 hours operation @ 25°C ppb vs. Aging / Day -0.2 +0.2ppb after 72 hours operation @ 25°C vs. Aging / Year -20 +20 ppb after 72 hours operation @ 25°C vs. Aging/ 20 Years -300 +300 after 72 hours operation @ 25°C ppb Retrace² -10 +10 ppb 5 to ± 10 ppb of final frequency (1 hour reading) Warm-up Time minutes @ +25°C

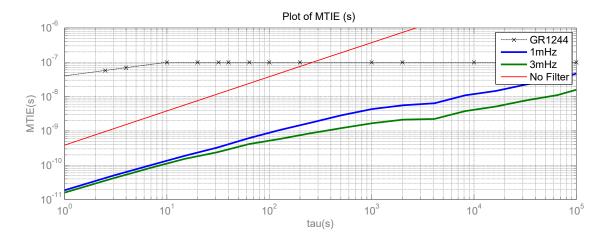
Performance Specifications

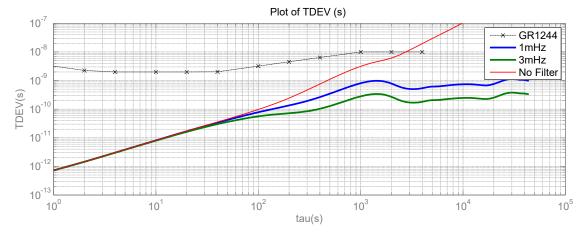
		Phase !	Stability (at	10 MHz)		
Parameter	Min	Typical	Max	Units	Condition	
		Addi	tional Paraı	meters		
MTIE 1 s MTIE 10 s MTIE 100 s MTIE 1000 s		0.02 0.1 1.0 5.0		ns ns ns ns	Wander Generation per GR1244, systo formance when locked through a 1m bandwidth, see typical performance	nHz loop
TDEV 1 s TDEV 10 s TDEV 100s TDEV 1000s		0.001 0.008 0.1 1		ns ns ns ns	Wander Generation per GR1244, systo formance when locked through a 1m bandwidth, see typical performance	nHz İoop
Phase Noise			-85 -115 -135 -145 -150	dBc/Hz dBc/Hz dBc/Hz dBc/Hz dBc/Hz	1 Hz 10 Hz 100 Hz 1 kHz 10 kHz	
For lower phase noise, please revi	iew the OX-174	1 datasheet.				
g-sensitivity				1	ppb/g	

g-sensitivity of 0.5 ppb/g available in this package size. Please contact factory for ordering information. For g-sensitivity <0.5 ppb/g, please review the OX-043 series.

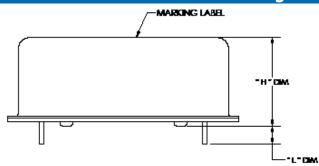
Supply Voltage (Vs)					
Parameter	Min	Typical	Max	Units	Condition
6 1 1/1 (1/2)	3.135	3.3	3.465	VDC	
Supply Voltage (Vs)	4.75	5.0	5.25	VDC	
			3.5	Watts	during warm-up, all temperatures
Dower Consumption			1.5	Watts	steady state @ +25°C
Power Consumption		3.3		Watts	steady state @ -40°C
		0.5		Watts	steady state @ +85°C
RF Output					
Start Time		1		S	time required to achieve 90% of amplitude
Signal [standard]		HCMOS			
Load		15		pF	
Signal Level (Vol)			0.4	VDC	with Vs=3.3V
Signal Level (Vol)			0.5		with Vs=5.0V
Signal Level (Voh)	2.4			VDC	with Vs=3.3V
Signal Level (Voh)	3.5				with Vs=5.0V
Duty Cycle	45		55	%	@ (Voh-Vol)/2
Frequency Tuning (EFC)					
Tuning Range		Fixed OCX	D; No adjust		

Absolute Maximum Ratings					
Supply Voltage (Vs)			6.5	VDC	with Vs=3.3 & 5.0 VDC
Output Load			50	рF	
Operable Temperature Range	-55		+95	°C	Operable temperature range implies the device will continue to operate with no long-term damage to unit; however, it will not be specification compliant outside the operating temperature range.
Environmental and Product Classification					on
Shock (Endurance)	MIL-STD-202, Method 213, Condition J, 30g 11 ms				
Sine Vibration (Endurance)	MIL-STD-202, Method 201 and 204, Condition A, except 5g to 500 Hz, 1 sweep each axis				
Random Vibration (Endurance)	MIL-STD-202, Method 214, Condition I-D				
Humidity	MIL-STD-202, Method 103, Condition B, 100% rh				
Seal	MIL-STD-202, Method 112, Condition D, hermetic, washable				
Altitude	MIL-STD-202, Method 105, sea level to space				
Resistance to Soldering Heat	MIL-STD-202, Method 210, Condition A,B,C				
Terminal Strength	MIL-STD-202, Method 211, Condition C (5 bends at 45°, 2 lbs)				
Moisture Sensitive Level	1				
RoHS	6 (fully compliant)				
Storage Temperature Range	-55		+125	°C	
Weight			25	g	

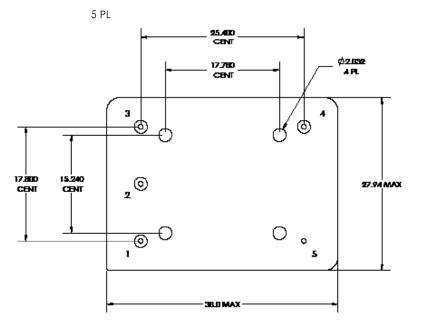




Outline Drawing / Enclosure



Through hole Package configuration A				
	Height "H"	Pin Length "L"		
0	18.2 max	4.5 mm min		
factory.	l height optio er height redu	ns available contact uces stability		



	Pin Connections
1,2	No Connect
3	Supply Voltage Input (VS)
4	RF Output
5	Ground (Case)

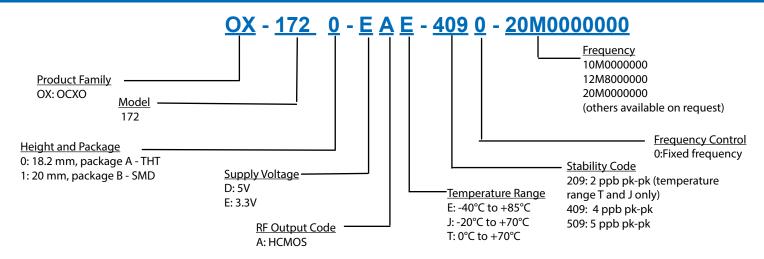
Dimensions in mm

	*H"
SEATING PLANE	
37.0±0.2	
1.7	4
2.5	,
7 6 5 4 17.8±0.1	
27.9±0.1	

Surface mount Package configuration B					
	Height "H"	Pin Length "L"			
1	20.3 max	n/a			
Additional height options available contact factory . Note - lower height reduces stability					

Pin	Connections
1,2,4,5,6,7, 11,12,13	No Connect
3	Supply Voltage Input (Vs)
8	RF Output
9,10	Ground (Case)

Ordering Information³



Additional Ordering Options

Additional ordering options available include custom aging rates, custom temperature ranges, custom temperature stabilities, custom phase noise requirements, sine wave option, improved g-sensitivity, and oscillators with EFC and reference voltages. These modifications require a custom dash number - please contact the factory for additional information.

Design Tools

Microsemi stocks the following items for small orders and prototype development:
OX-1720-EAE-4090-20M0000000
Microsemi stocks the following evaluation board for this product:
OCXO Evaluation Board
Application Notes:
None

Notes:

- Unless otherwise stated, all values are valid after warm-up time and refer to typical conditions for supply voltage, load, and temperature (25°C).
- Retrace is defined as the frequency difference between the end of two 24 hour on power periods with a 24 hour off period in between while at a constant temperature.
- Not all options and codes available at all frequencies.



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Microsemi Headquarters

One Enterprise, Aliso Viejo, CA 92656 USA Within the USA: +1 (800) 713-4113 Outside the USA: +1 (949) 380-6100 Sales: +1 (949) 380-6136 Fax: +1 (949) 215-4996 email: sales.support@microsemi.com www.microsemi.com

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